Low-power 3-input OR-AND gate Rev. 3 — 11 October 2010

Product data sheet

#### **General description** 1.

The 74AUP1G3208 provides the Boolean function:  $Y = (A + B) \times C$ . The user can choose the logic functions OR, AND and OR-AND. All inputs can be connected to  $V_{CC}$  or GND.

Schmitt trigger action at all inputs makes the circuit tolerant to slower input rise and fall times across the entire  $V_{CC}$  range from 0.8 V to 3.6 V.

This device ensures a very low static and dynamic power consumption across the entire  $V_{CC}$  range from 0.8 V to 3.6 V.

This device is fully specified for partial power-down applications using I<sub>OFF</sub>. The I<sub>OFF</sub> circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

#### **Features and benefits** 2.

- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- Complies with JEDEC standards:
  - ◆ JESD8-12 (0.8 V to 1.3 V)
  - JESD8-11 (0.9 V to 1.65 V)
  - JESD8-7 (1.2 V to 1.95 V)
  - JESD8-5 (1.8 V to 2.7 V)
  - JESD8-B (2.7 V to 3.6 V)
- ESD protection:
  - HBM JESD22-A114F Class 3A exceeds 5000 V
  - MM JESD22-A115-A exceeds 200 V
  - CDM JESD22-C101E exceeds 1000 V
- Low static power consumption;  $I_{CC} = 0.9 \mu A$  (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10 % of V<sub>CC</sub>
- I<sub>OFF</sub> circuitry provides partial Power-down mode operation
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C



Low-power 3-input OR-AND gate

## 3. Ordering information

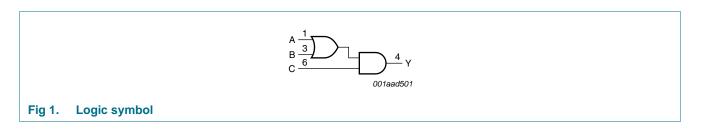
Table 1. Ordering	g information								
Type number	Package								
	Temperature range	Name	Description	Version					
74AUP1G3208GW	–40 °C to +125 °C	SC-88	plastic surface-mounted package; 6 leads	SOT363					
74AUP1G3208GM	–40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 $\times$ 1.45 $\times$ 0.5 mm	SOT886					
74AUP1G3208GF	–40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 $\times$ 1 $\times$ 0.5 mm	SOT891					
74AUP1G3208GN	–40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body $0.9 \times 1.0 \times 0.35$ mm	SOT1115					
74AUP1G3208GS	–40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body $1.0 \times 1.0 \times 0.35$ mm	SOT1202					

### 4. Marking

Table 2. Marking	
Type number	Marking code <sup>[1]</sup>
74AUP1G3208GW	a2
74AUP1G3208GM	a2
74AUP1G3208GF	a2
74AUP1G3208GN	a2
74AUP1G3208GS	a2

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

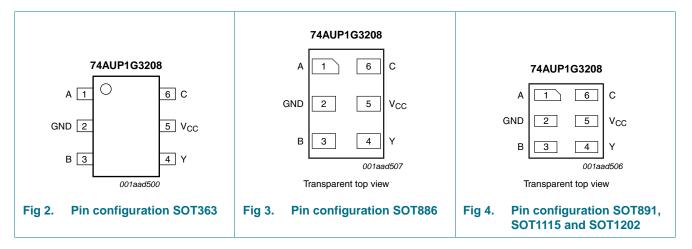
### 5. Functional diagram



Low-power 3-input OR-AND gate

### 6. Pinning information

### 6.1 Pinning



### 6.2 Pin description

Table 3.	Pin description	
Symbol	Pin	Description
A	1	data input A
GND	2	ground (0 V)
В	3	data input B
Y	4	data output Y
V <sub>CC</sub>	5	supply voltage
С	6	data input C

### 7. Functional description

#### Table 4. Function table<sup>[1]</sup> Input Output С в Υ Α L L L L L L Н L Н L L L L Н Н L Н L L L Н L Н Н Н Н L Н н н Н Н

[1] H = HIGH voltage level; L = LOW voltage level.

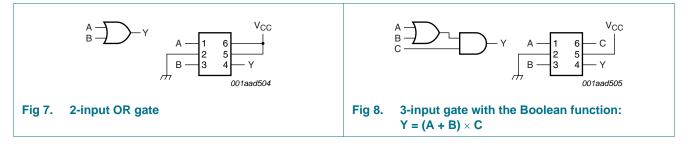
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### 7.1 Logic configurations

#### Table 5. Function selection table

Logic function	Figure
2-input AND	see Figure 5 and Figure 6
2-input OR	see Figure 7
3-input gate with the Boolean function: $Y = (A + B) \times C$	see Figure 8





### 8. Limiting values

#### Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

				10	,
Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+4.6	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < 0 V	-50	-	mA
VI	input voltage		<u>[1]</u> –0.5	+4.6	V
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < 0 V	-50	-	mA
Vo	output voltage	Active mode and Power-down mode	<u>[1]</u> –0.5	+4.6	V
lo	output current	$V_{O} = 0 V$ to $V_{CC}$	-	±20	mA
I <sub>CC</sub>	supply current		-	50	mA
I <sub>GND</sub>	ground current		-50	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	$T_{amb}$ = -40 °C to +125 °C	[2] _	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SC-88 packages: above 87.5  $^\circ\text{C}$  the value of Ptot derates linearly with 4.0 mW/K.

For XSON6 packages: above 118 °C the value of Ptot derates linearly with 7.8 mW/K.

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## 9. Recommended operating conditions

Table 7.	Recommended operating conditi	ons			
Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		0.8	3.6	V
VI	input voltage		0	3.6	V
Vo	output voltage	Active mode	0	V <sub>CC</sub>	V
		Power-down mode; $V_{CC} = 0 V$	0	3.6	V
T <sub>amb</sub>	ambient temperature		-40	+125	°C
$\Delta t / \Delta V$	input transition rise and fall rate	$V_{CC} = 0.8 V \text{ to } 3.6 V$	0	200	ns/V

## **10. Static characteristics**

#### Table 8. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

0.70 × V <sub>CC</sub> 1.95 V 0.65 × V <sub>CC</sub> 2.7 V 1.6		-	V
1.95 V $0.65 \times V_{CC}$		-	V
	-		V
2.7 V 1.6		-	V
	-	-	V
3.6 V 2.0	-	-	V
-	-	$0.30\times V_{CC}$	V
1.95 V -	-	$0.35 \times V_{CC}$	V
2.7 V -	-	0.7	V
3.6 V -	-	0.9	V
$V_{CC} = 0.8 V \text{ to } 3.6 V$ $V_{CC} - 0.1$	-	-	V
; $V_{CC} = 1.1 \text{ V}$ $0.75 \times V_{CC}$	-	-	V
; $V_{CC} = 1.4 \text{ V}$ 1.11	-	-	V
; $V_{CC} = 1.65 \text{ V}$ 1.32	-	-	V
; $V_{CC} = 2.3 V$ 2.05	-	-	V
; $V_{CC} = 2.3 V$ 1.9	-	-	V
; $V_{CC} = 3.0 \text{ V}$ 2.72	-	-	V
; $V_{CC} = 3.0 \text{ V}$ 2.6	-	-	V
$V_{\rm CC} = 0.8 \text{V} \text{ to } 3.6 \text{V}$ -	-	0.1	V
V <sub>CC</sub> = 1.1 V -	-	$0.3\times V_{CC}$	V
V <sub>CC</sub> = 1.4 V -	-	0.31	V
V <sub>CC</sub> = 1.65 V -	-	0.31	V
V <sub>CC</sub> = 2.3 V -	-	0.31	V
V <sub>CC</sub> = 2.3 V -	-	0.44	V
V <sub>CC</sub> = 3.0 V -	-	0.31	V
V <sub>CC</sub> = 3.0 V -	-	0.44	V
	2.7 V       - $3.6 V$ -         V <sub>CC</sub> = 0.8 V to $3.6 V$ V <sub>CC</sub> - 0.1         x; V <sub>CC</sub> = 1.1 V       0.75 × V <sub>CC</sub> x; V <sub>CC</sub> = 1.4 V       1.11         x; V <sub>CC</sub> = 1.65 V       1.32         x; V <sub>CC</sub> = 2.3 V       2.05         x; V <sub>CC</sub> = 3.0 V       2.72         x; V <sub>CC</sub> = 3.0 V       2.6         V <sub>CC</sub> = 1.1 V       -         V <sub>CC</sub> = 1.4 V       -         V <sub>CC</sub> = 1.65 V       -         V <sub>CC</sub> = 2.3 V       -         V <sub>CC</sub> = 2.3 V       -         V <sub>CC</sub> = 2.3 V       -	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	$2.7 \vee$ 0.7 $3.6 \vee$ 0.9 $V_{CC} = 0.8 \vee$ to $3.6 \vee$ $V_{CC} - 0.1$ - $x; \vee_{CC} = 1.1 \vee$ $0.75 \times \vee_{CC}$ - $x; \vee_{CC} = 1.4 \vee$ $1.11$ - $x; \vee_{CC} = 1.65 \vee$ $1.32$ - $x; \vee_{CC} = 2.3 \vee$ $2.05$ - $x; \vee_{CC} = 3.0 \vee$ $2.72$ - $x; \vee_{CC} = 3.0 \vee$ $2.66$ - $v; \vee_{CC} = 1.4 \vee$ -0.1 $\vee_{CC} = 1.4 \vee$ -0.31 $\vee_{CC} = 1.4 \vee$ $\vee_{CC} = 1.65 \vee$ $\vee_{CC} = 2.3 \vee$ $\vee_{CC} = 2.3 \vee$ $\vee_{CC} = 2.3 \vee$ $\vee_{CC} = 3.0 \vee$ <

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Symbol	Parameter	Conditions	Min	Тур	Max	Uni
l <sub>l</sub>	input leakage current	$V_I = GND$ to 3.6 V; $V_{CC} = 0$ V to 3.6 V	-	-	±0.1	μA
I <sub>OFF</sub>	power-off leakage current	$V_{I}$ or $V_{O} = 0$ V to 3.6 V; $V_{CC} = 0$ V	-	-	±0.2	μΑ
$\Delta I_{OFF}$	additional power-off leakage current	$V_1$ or $V_0 = 0$ V to 3.6 V; $V_{CC} = 0$ V to 0.2 V	-	-	±0.2	μA
I <sub>CC</sub>	supply current	$V_{I} = GND \text{ or } V_{CC}; I_{O} = 0 \text{ A};$ $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	0.5	μA
∆l <sub>CC</sub>	additional supply current		-	-	40	μA
CI	input capacitance	$V_{CC}$ = 0 V to 3.6 V; $V_{I}$ = GND or $V_{CC}$	-	0.8	-	pF
Co	output capacitance	$V_O = GND; V_{CC} = 0 V$	-	1.7	-	pF
T <sub>amb</sub> = -4	10 °C to +85 °C					
V <sub>IH</sub>	HIGH-level input voltage	$V_{CC} = 0.8 V$	$0.70 \times V_{CC}$	-	-	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	$0.65  imes V_{CC}$	-	-	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.6	-	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 0.8 V	-	-	$0.30 \times V_{CC}$	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	-	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	-	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	V
V <sub>OH</sub>	HIGH-level output voltage	$V_{I} = V_{IH}$ or $V_{IL}$				
		$I_{O} = -20 \ \mu A; V_{CC} = 0.8 \ V \text{ to } 3.6 \ V$	V <sub>CC</sub> – 0.1	-	-	V
		I <sub>O</sub> = -1.1 mA; V <sub>CC</sub> = 1.1 V	$0.7 \times V_{CC}$	-	-	V
		$I_0 = -1.7 \text{ mA}; V_{CC} = 1.4 \text{ V}$	1.03	-	-	V
		I <sub>O</sub> = -1.9 mA; V <sub>CC</sub> = 1.65 V	1.30	-	-	V
		$I_0 = -2.3 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.97	-	-	V
		$I_0 = -3.1 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.85	-	-	V
		$I_0 = -2.7 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.67	-	-	V
		$I_0 = -4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.55	-	-	V
V <sub>OL</sub>	LOW-level output voltage	$V_{I} = V_{IH}$ or $V_{IL}$				
		$I_0 = 20 \ \mu A; V_{CC} = 0.8 \ V \text{ to } 3.6 \ V$	-	-	0.1	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	$0.3 \times V_{CC}$	V
		$I_0 = 1.7 \text{ mA}; V_{CC} = 1.4 \text{ V}$	-	-	0.37	V
		$I_0 = 1.9 \text{ mA}; V_{CC} = 1.65 \text{ V}$	-	-	0.35	V
		$I_0 = 2.3 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	-	0.33	V
		$I_0 = 3.1 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	-	0.45	V
		$I_0 = 2.7 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.33	V
		$I_0 = 4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.45	V
I <sub>I</sub>	input leakage current	$V_{I} = GND \text{ to } 3.6 \text{ V}; V_{CC} = 0 \text{ V to } 3.6 \text{ V}$	-	-	±0.5	μA
I <sub>OFF</sub>	power-off leakage current	$V_{\rm I}$ or $V_{\rm O} = 0$ V to 3.6 V; $V_{\rm CC} = 0$ V	-	-	±0.5	μA
$\Delta I_{OFF}$	additional power-off leakage current	$V_{I} \text{ or } V_{O} = 0 \text{ V to } 3.6 \text{ V};$ $V_{CC} = 0 \text{ V to } 0.2 \text{ V}$	-	-	±0.6	μΑ

#### Table 8 Static characteristics continued

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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
СС	supply current	$\label{eq:VI} \begin{array}{l} V_{I} = GND \text{ or } V_{CC}; \ I_{O} = 0 \ A; \\ V_{CC} = 0.8 \ V \ to \ 3.6 \ V \end{array}$	-	-	0.9	μΑ
∆l <sub>CC</sub>	additional supply current	$V_{I} = V_{CC} - 0.6 \text{ V}; I_{O} = 0 \text{ A};$ $V_{CC} = 3.3 \text{ V}$	-	-	50	μA
T <sub>amb</sub> = -4	40 °C to +125 °C					
VIH	HIGH-level input voltage	$V_{CC} = 0.8 V$	$0.75\times V_{CC}$	-	-	V
		$V_{CC}$ = 0.9 V to 1.95 V	$0.70\times V_{CC}$	-	-	V
		$V_{CC}$ = 2.3 V to 2.7 V	1.6	-	-	V
		$V_{CC} = 3.0 \text{ V} \text{ to } 3.6 \text{ V}$	2.0	-	-	V
VIL	LOW-level input voltage	$V_{CC} = 0.8 V$	-	-	$0.25\times V_{CC}$	V
		$V_{CC} = 0.9 V$ to 1.95 V	-	-	$0.30 \times V_{CC}$	V
		$V_{CC}$ = 2.3 V to 2.7 V	-	-	0.7	V
		$V_{CC} = 3.0 \text{ V} \text{ to } 3.6 \text{ V}$	-	-	0.9	V
V <sub>он</sub>	HIGH-level output voltage	$V_{I} = V_{IH} \text{ or } V_{IL}$				
		$I_{O}$ = –20 $\mu A; \ V_{CC}$ = 0.8 V to 3.6 V	V <sub>CC</sub> - 0.11	-	-	V
		$I_0 = -1.1 \text{ mA}; V_{CC} = 1.1 \text{ V}$	$0.6\times V_{CC}$	-	-	V
		$I_{O} = -1.7 \text{ mA}; V_{CC} = 1.4 \text{ V}$	0.93	-	-	V
		$I_{O} = -1.9 \text{ mA}; V_{CC} = 1.65 \text{ V}$	1.17	-	-	V
		$I_{O} = -2.3 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.77	-	-	V
		$I_{O} = -3.1 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.67	-	-	V
		$I_0 = -2.7 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.40	-	-	V
		$I_{O} = -4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.30	-	-	V
Vol	LOW-level output voltage	$V_{I} = V_{IH} \text{ or } V_{IL}$				
		$I_{O}$ = 20 µA; $V_{CC}$ = 0.8 V to 3.6 V	-	-	0.11	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	$0.33 \times V_{CC}$	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.41	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.39	V
		$I_0 = 2.3 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	-	0.36	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.50	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.36	V
		$I_0 = 4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.50	V
I	input leakage current	$V_{I} = GND \text{ to } 3.6 \text{ V}; V_{CC} = 0 \text{ V to } 3.6 \text{ V}$	-	-	±0.75	μA
OFF	power-off leakage current	$V_{\rm I}$ or $V_{\rm O} = 0$ V to 3.6 V; $V_{\rm CC} = 0$ V	-	-	±0.75	μΑ
∆I <sub>OFF</sub>	additional power-off leakage current	$V_{I} \text{ or } V_{O} = 0 \text{ V to } 3.6 \text{ V};$ $V_{CC} = 0 \text{ V to } 0.2 \text{ V}$	-	-	±0.75	μΑ
сс	supply current	$V_I = GND \text{ or } V_{CC}; I_O = 0 \text{ A};$ $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	1.4	μA
∆l <sub>CC</sub>	additional supply current	$V_{I} = V_{CC} - 0.6 \text{ V}; I_{O} = 0 \text{ A};$ $V_{CC} = 3.3 \text{ V}$	-	-	75	μΑ

### Table 8. Static characteristics ...continued

## 11. Dynamic characteristics

#### **Dynamic characteristics** Table 9.

Voltages are referenced to GND (ground = 0 V); for test circuit see Figure 10.

Symbol Parameter		Conditions		25 °C			–40 °C to +125 °C		
			Min	Typ <mark>[1]</mark>	Max	Min	Max (85 °C)	Max (125 °C)	
C <sub>L</sub> = 5 p	F						1		
pd	propagation delay	A, B or C to Y; see Figure 9	[2]						
		$V_{CC} = 0.8 V$	-	18.5	-	-	-	-	ns
		$V_{CC} = 1.1 \text{ V to } 1.3 \text{ V}$	2.2	5.4	10.6	2.2	10.9	11.1	ns
		$V_{CC}$ = 1.4 V to 1.6 V	1.9	3.8	6.4	1.8	6.9	7.2	ns
		$V_{CC}$ = 1.65 V to 1.95 V	1.5	3.1	5.1	1.4	5.6	5.9	ns
		$V_{CC}$ = 2.3 V to 2.7 V	1.3	2.4	3.7	1.2	4.1	4.4	ns
		$V_{CC} = 3.0 \text{ V} \text{ to } 3.6 \text{ V}$	1.2	2.2	3.2	1.1	3.4	3.6	ns
C <sub>L</sub> = 10	pF								
t <sub>pd</sub>	propagation delay	A, B or C to Y; see Figure 9	[2]						
		$V_{CC} = 0.8 V$	-	22.1	-				ns
		$V_{CC}$ = 1.1 V to 1.3 V	2.6	6.3	12.4	2.5	12.8	13.1	ns
		$V_{CC}$ = 1.4 V to 1.6 V	2.3	4.4	7.4	2.1	8.0	8.4	ns
		$V_{CC}$ = 1.65 V to 1.95 V	2.0	3.6	5.9	1.8	6.4	6.8	ns
		$V_{CC}$ = 2.3 V to 2.7 V	1.7	3.0	4.4	1.6	4.8	5.1	ns
		$V_{CC} = 3.0 \text{ V} \text{ to } 3.6 \text{ V}$	1.6	2.7	3.9	1.4	4.2	4.4	ns
C <sub>L</sub> = 15	pF								
t <sub>pd</sub>	propagation delay	A, B or C to Y; see Figure 9	[2]						
		$V_{CC} = 0.8 V$	-	25.6	-	-	-	-	ns
		$V_{CC}$ = 1.1 V to 1.3 V	3.0	7.1	14.1	2.8	14.6	14.9	ns
		$V_{CC}$ = 1.4 V to 1.6 V	2.6	5.0	8.4	2.4	9.1	9.5	ns
		$V_{CC}$ = 1.65 V to 1.95 V	2.2	4.1	6.7	2.1	7.4	7.8	ns
		$V_{CC}$ = 2.3 V to 2.7 V	2.0	3.4	5.0	1.9	5.5	5.9	ns
		$V_{CC}$ = 3.0 V to 3.6 V	1.9	3.2	4.5	1.7	4.8	5.0	ns
C <sub>L</sub> = 30	pF								
t <sub>pd</sub>	propagation delay	A, B or C to Y; see Figure 9	[2]						
		$V_{CC} = 0.8 V$	-	34.1	-	-	-	-	ns
		$V_{CC} = 1.1 \text{ V to } 1.3 \text{ V}$	3.9	9.3	18.9	3.7	19.7	20.1	ns
		$V_{CC} = 1.4 \text{ V}$ to 1.6 V	3.4	6.5	11.0	3.2	12.1	12.7	ns
		$V_{CC}$ = 1.65 V to 1.95 V	3.0	5.4	8.9	2.9	9.7	10.3	ns
		$V_{CC}$ = 2.3 V to 2.7 V	2.8	4.5	6.5	2.6	7.1	7.5	ns
		$V_{CC} = 3.0 \text{ V} \text{ to } 3.6 \text{ V}$	2.6	4.3	5.8	2.4	6.4	6.7	ns

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Symbol	Parameter	Conditions	25 °C			–40 °C to +125 °C			Unit
			Min	Typ <mark>[1]</mark>	Max	Min	Max (85 °C)	Max (125 °C)	_
C <sub>L</sub> = 5 p	F, 10 pF, 15 pF and	30 pF							
C <sub>PD</sub> power dissipation		$f_i = 1 \text{ MHz}; V_1 = \text{GND to } V_{\text{CC}}$ [3][4]							
	capacitance	$V_{CC} = 0.8 V$	-	2.6	-	-	-	-	pF
		$V_{CC} = 1.1 \text{ V} \text{ to } 1.3 \text{ V}$	-	2.7	-	-	-	-	pF
		$V_{CC} = 1.4 \text{ V} \text{ to } 1.6 \text{ V}$	-	2.8	-	-	-	-	pF
		$V_{CC}$ = 1.65 V to 1.95 V	-	3.0	-	-	-	-	pF
		$V_{CC}$ = 2.3 V to 2.7 V	-	3.5	-	-	-	-	pF
		$V_{CC} = 3.0 \text{ V}$ to 3.6 V	-	4.0	-	-	-	-	pF

#### Table 9. Dynamic characteristics ... continued

[1] All typical values are measured at nominal V<sub>CC</sub>.

[2]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .

[3] All specified values are the average typical values over all stated loads.

[4]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ ).

 $P_{D} = C_{PD} \times V_{CC}^{2} \times f_{i} \times N + \Sigma (C_{L} \times V_{CC}^{2} \times f_{o}) \text{ where:}$ 

 $f_i$  = input frequency in MHz;

 $f_0$  = output frequency in MHz;

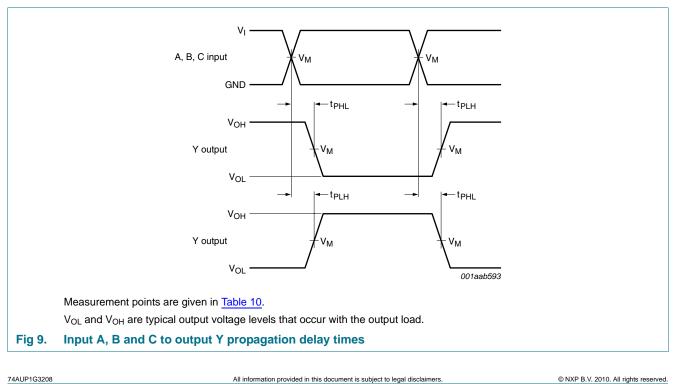
 $C_L$  = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

 $\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.

### 12. Waveforms



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### **NXP Semiconductors**

Table 10. Measurement points

Output

# 74AUP1G3208

#### Low-power 3-input OR-AND gate

	V <sub>M</sub> 0.5 × V <sub>CC</sub>	V <sub>M</sub> 0.5 × V <sub>CC</sub>	V <sub>I</sub> V <sub>CC</sub> V <sub>EXT</sub>	t <sub>r</sub> = t <sub>f</sub> ≤ 3.0 ns
	Vi	Vcc	V <sub>EXT</sub>	≤ 3.0 ns
	G		Ц	
	G		Ц	
	G		Ц	
	G			
	G	V O	1 J K12	
		╶┟└─┘Ť		
	r <del>h</del> ı	<i>hh hh h</i> h	rh rh	
			001aac521	
data is given in Ta	able 11.			
nitions for test circ	uit:			
Load resistance.				
Load capacitance	e including jig and probe	e capacitance.		
Termination resis	tance should be equal t	o the output impedan	ce Z <sub>o</sub> of the pulse generation	ator.
<sub>Γ</sub> = External voltag	e for measuring switchi	ng times.		
t circuit for mea	asuring switching ti	mes		
	nitions for test circ Load resistance. Load capacitance Termination resis T = External voltag	ELoad capacitance including jig and probe Termination resistance should be equal t T = External voltage for measuring switchi	data is given in <u>Table 11</u> . nitions for test circuit: - Load resistance. - Load capacitance including jig and probe capacitance.	$\begin{array}{l} & 001aac521\\ \\ \text{data is given in } \underline{\text{Table 11}}.\\ \\ \text{nitions for test circuit:}\\ \\ \text{Load resistance.}\\ \\ \\ \text{Load capacitance including jig and probe capacitance.}\\ \\ \\ \text{Termination resistance should be equal to the output impedance } Z_{o} \text{ of the pulse gener}\\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \end{array}$

Input

#### Table 11. Test data

Supply voltage	Load		V <sub>EXT</sub>		
V <sub>CC</sub>	CL	R <sub>L</sub> [1]	t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PZH</sub> , t <sub>PHZ</sub>	t <sub>PZL</sub> , t <sub>PLZ</sub>
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 k $\Omega$ or 1 M $\Omega$	open	GND	$2 \times V_{CC}$

[1] For measuring enable and disable times  $R_L = 5 k\Omega$ , for measuring propagation delays, setup and hold times and pulse width  $R_L = 1 M\Omega$ .

# Supply voltage

Low-power 3-input OR-AND gate

### 13. Package outline

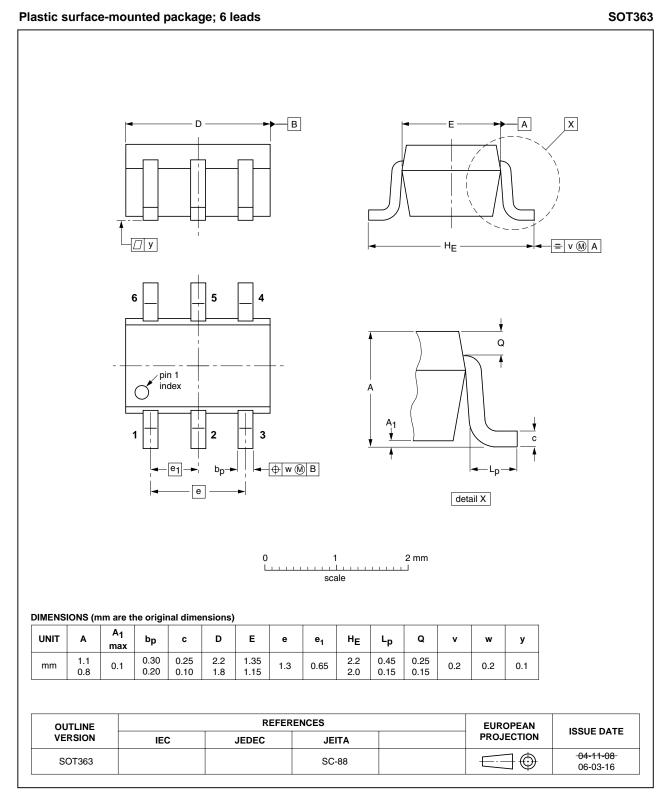
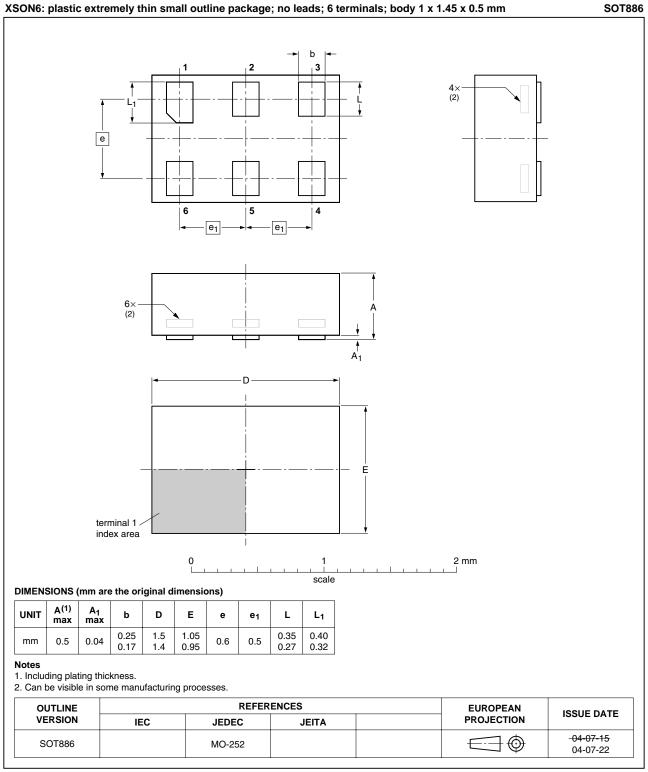


Fig 11. Package outline SOT363 (SC-88)

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Low-power 3-input OR-AND gate

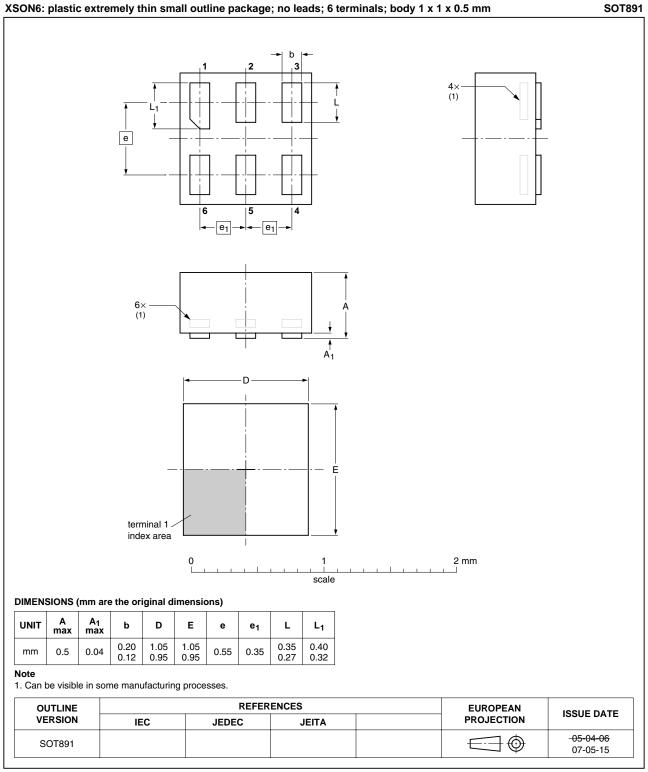


XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

Fig 12. Package outline SOT886 (XSON6)

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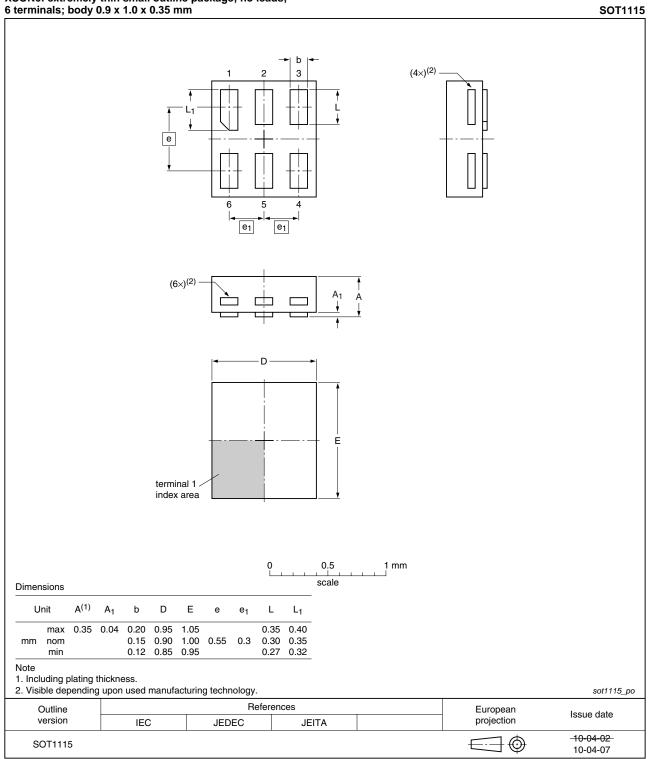
Low-power 3-input OR-AND gate



#### Fig 13. Package outline SOT891 (XSON6)

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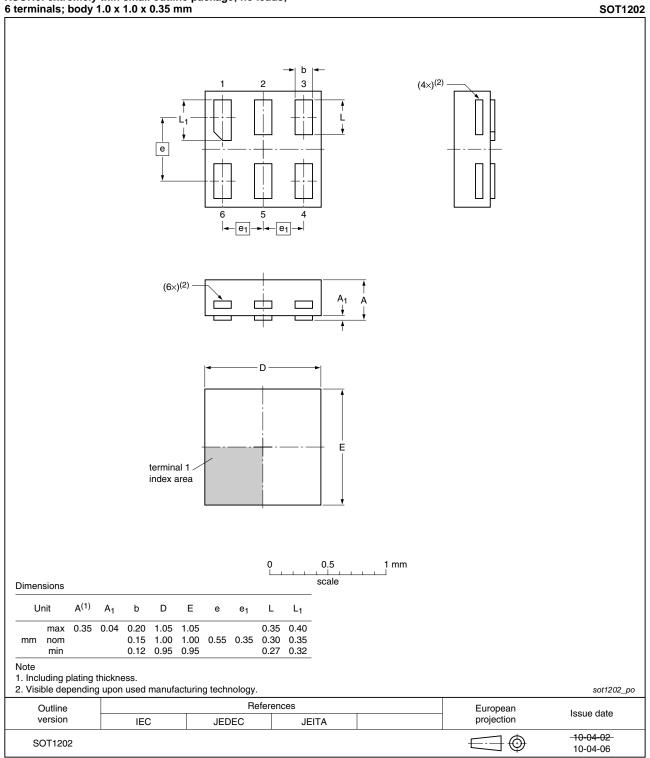
Low-power 3-input OR-AND gate



# XSON6: extremely thin small outline package; no leads; 6 terminals; body 0.9 x 1.0 x 0.35 mm

Fig 14. Package outline SOT1115 (XSON6)

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# XSON6: extremely thin small outline package; no leads; 6 terminals; body 1.0 x 1.0 x 0.35 mm

Fig 15. Package outline SOT1202 (XSON6)

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Low-power 3-input OR-AND gate

## 14. Abbreviations

AcronymDescriptionCDMCharged Device ModelDUTDevice Under TestESDElectroStatic Discharge	
DUT Device Under Test	
ESD ElectroStatic Discharge	
HBM Human Body Model	
MM Machine Model	

## **15. Revision history**

story			
Release date	Data sheet status	Change notice	Supersedes
20101011	Product data sheet	-	74AUP1G3208 v.2
<ul> <li>Added type r</li> </ul>	number 74AUP1G3208GN (Se	OT1115/XSON6 packag	e).
<ul> <li>Added type r</li> </ul>	number 74AUP1G3208GS (Se	OT1202/XSON6 packag	je).
20090703	Product data sheet	-	74AUP1G3208 v.1
20061129	Product data sheet	-	-
	Release date 20101011 • Added type i 20090703	Release dateData sheet status20101011Product data sheet• Added type number 74AUP1G3208GN (So• Added type number 74AUP1G3208GS (So20090703Product data sheet	Release dateData sheet statusChange notice20101011Product data sheet-• Added type number 74AUP1G3208GN (SOT1115/XSON6 packag• Added type number 74AUP1G3208GS (SOT1202/XSON6 packag20090703Product data sheet

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Document status[1][2]	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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Product data sheet

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#### Low-power 3-input OR-AND gate

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Date of release: 11 October 2010 Document identifier: 74AUP1G3208